

SML0603-881-TR

Infrared

Surface Mount LED

1.6 × 0.8 × 0.8mm Chip LED

140° viewing angle

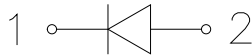
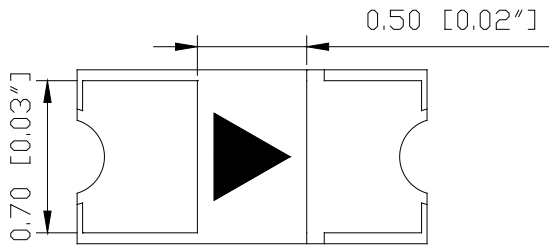
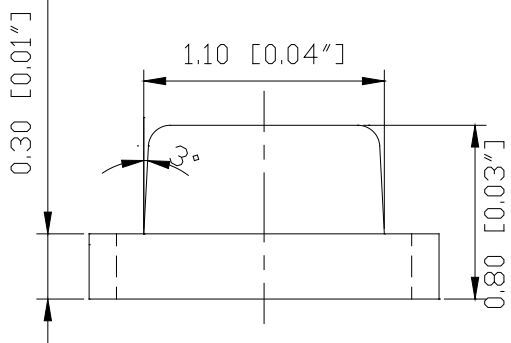
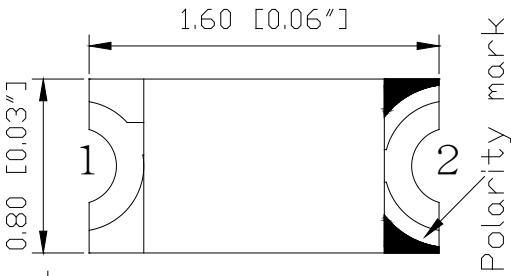
DWG BY:
SL / GP
04-19-13

R&D:
BJ
04-24-13

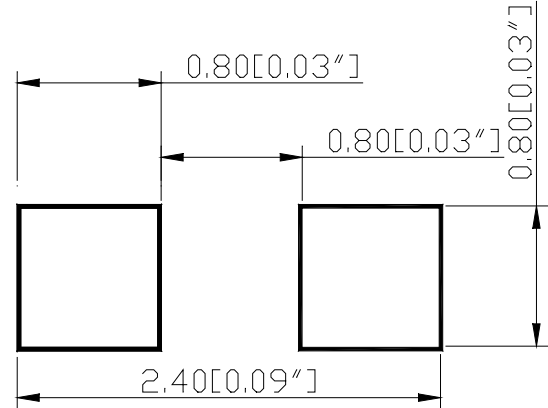
QA:
RD
04-24-13

REVISION LTR: -
ECR#: 041513-RTD01
04-19-13

Package outlines



RECOMMEND PAD LAYOUT



ITEM	MATERIALS
Resin (mold)	Epoxy
Lens color	Water transparent
Dice	GaAIAs/GaAIAs

NOTES:

1. All dimensions are in Millimeters (Inches).
2. Tolerance are $\pm 0.2\text{mm}$ (0.008inch) unless otherwise noted.

Absolute maximum ratings (T_A=25°C)

Parameter	Symbol	Value	Unit
Power dissipation	Pd	95	mW
Peak forward current Pulse width 100μs, duty cycle =1%	I _{fp}	1	A
Continuous forward current	I _f	50	mA
Reverse voltage	V _r	5	V
Operating temperature range	T _{op}	-40 ~+80	°C
Storage temperature range	T _{stg}	-40 ~+85	°C

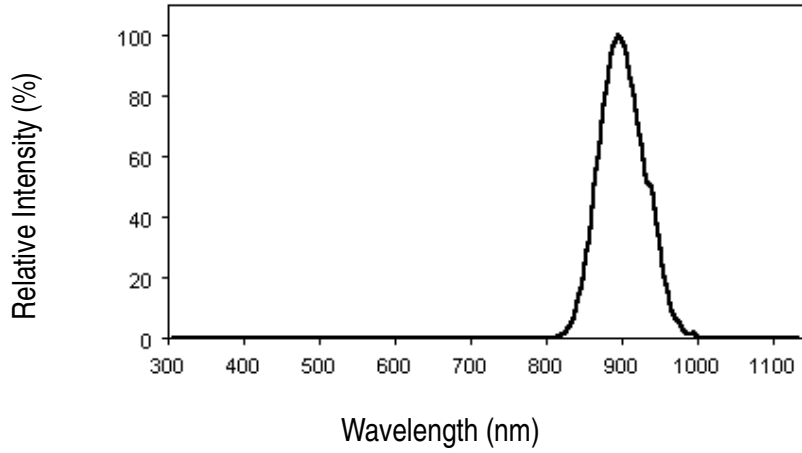
Electro-optical characteristics (T_A=25°C)

Parameter	Test Condition	Symbol	Value			Unit
			Min	Typ	Max	
Radiant incidence *1	I _f =20mA	E _e	--	0.35	--	mW/cm ²
Forward voltage	I _f =20mA	V _f	--	1.40	1.90	V
Reverse current	V _r =5V	I _r	--	--	10	μA
Peak wavelength	I _f =20mA	λ _p	--	880	--	nm
Spectral bandwidth	I _f =20mA	Δλ	--	70	--	nm
View angle	I _f =10mA	2θ 1/2	--	140	--	Deg

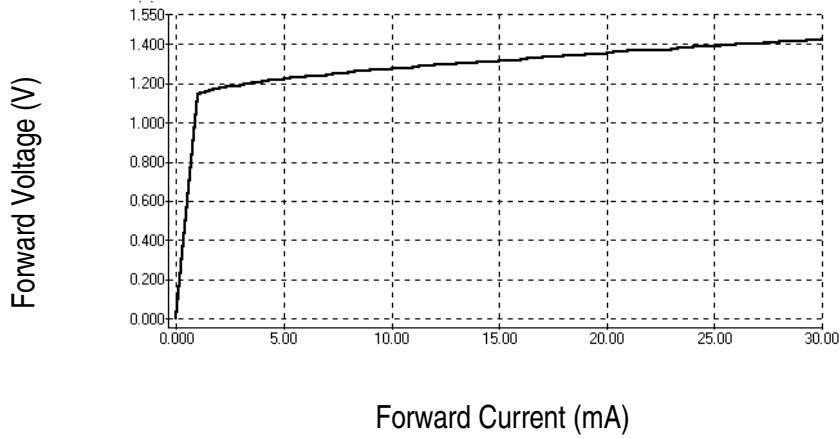
*1 Note: Radiant incidence tolerance is ±10%

OPTICAL CHARACTERISTIC CURVES

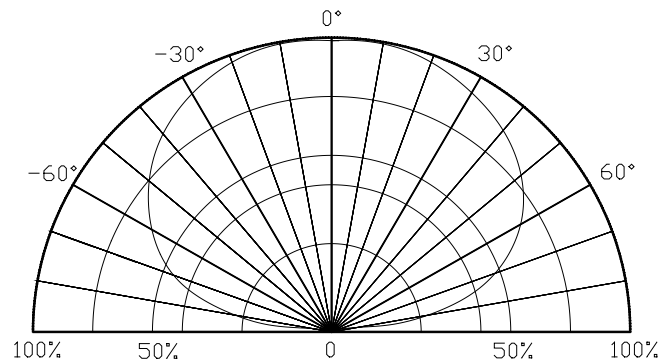
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage

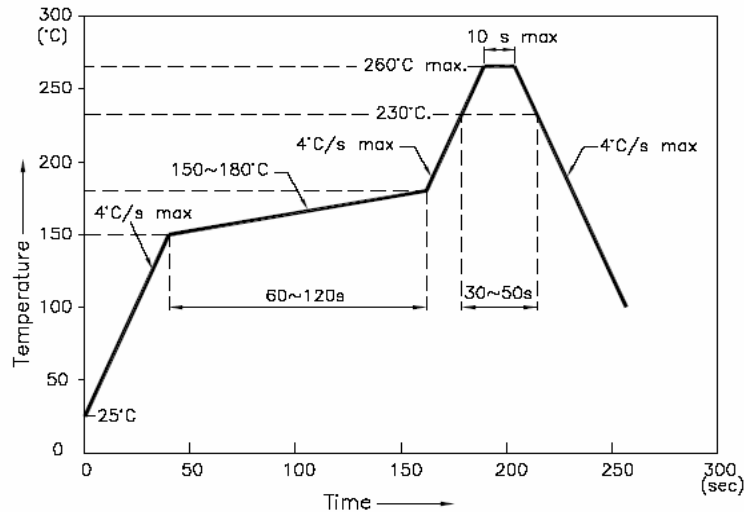


Directive Characteristics



Reflow Profile

■ Solder Reflow

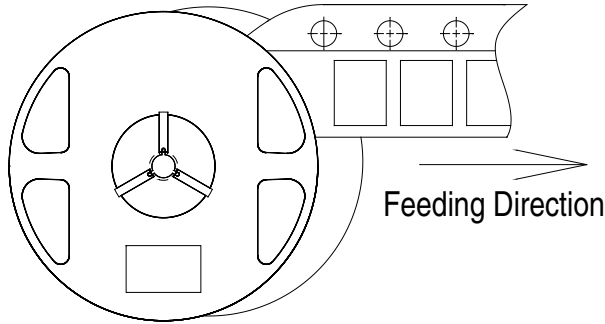


NOTES:

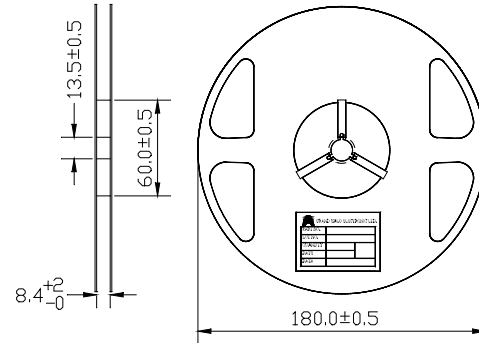
1. Recommended reflow temperature 245°C (±5°C). The soldering temperature should be limited to 260°C max.
2. Don't stress or scratch the epoxy resin while it is exposed to high temperature.
3. Recommended max. number of reflow cycles=1.
4. Allow for gradual coolin. Avoid quenching.

0603 Series SMD Chip LED Lamps Packaging Specifications

● **Feeding Direction**



● **Dimensions of Reel (Unit: mm)**



● **Dimensions of Tape (Unit: mm)**

